


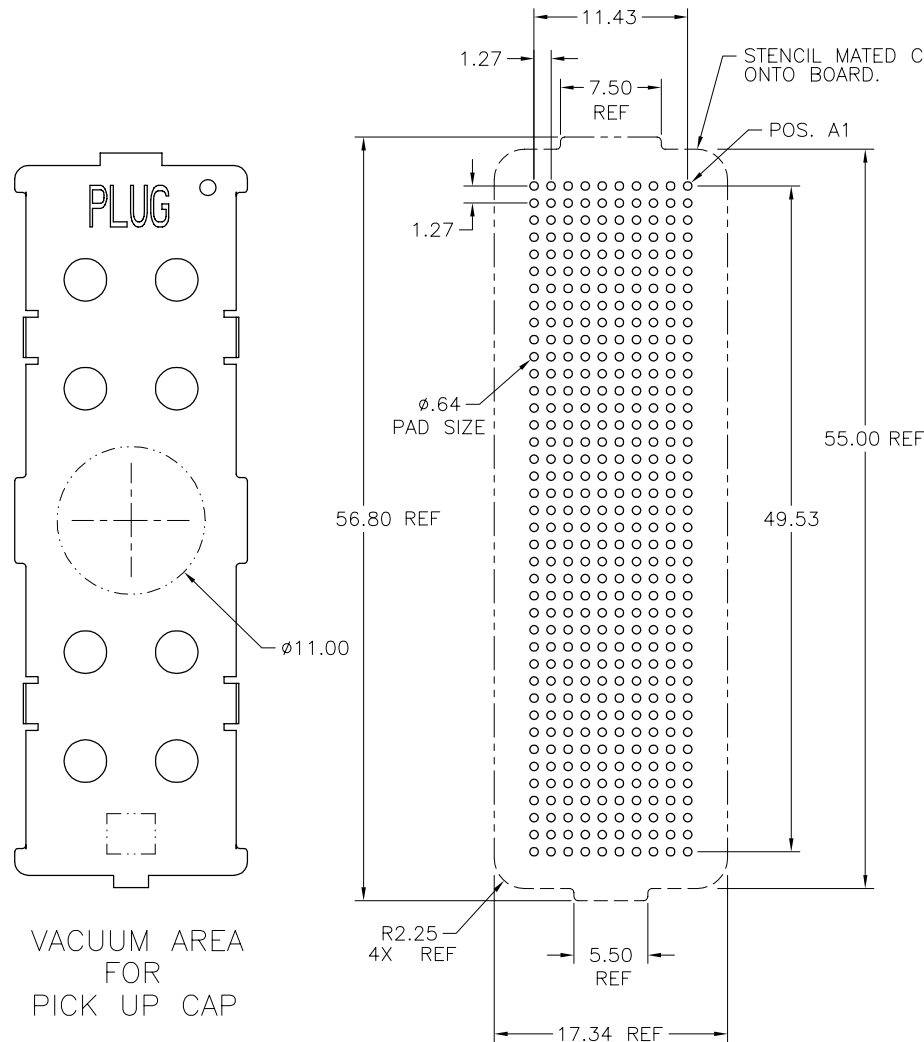
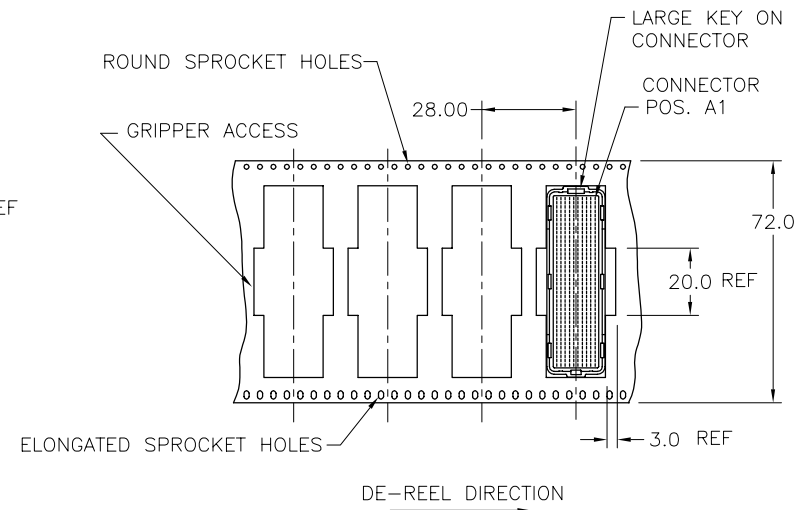



mat'l. code SEE NOTE 1				surface ASME Y14.5 ✓		tolerance ASME Y14.5		projection 		product family MEG-ARRAY													
ltr		ecn no		dr		date		tolerances unless otherwise specified						title									
J		V06-0560		LP		2006/07/17		angles		line to		X *3				0mm PLUG ASSY 10 x 40 = 400 POS.							
-		-		-		-		-		XX *13													
D		V20006		DRW		1/8/02		0° ±2'		line to		XXX *051											
E		V20486		DRW		3/12/02		dr		D.WAUGHEN		9.18.98				dwg no		sheet 1 of 3				size	
F		V21254		DAI		07/30/02		enrg		M.HAHN		9.18.98				84740		A4					
G		V03-0681		DAI		06/23/03		chr		M.HAHN		9.18.98											
H		V04-0940		VS		10/18/04		appd		M.HAHN		9.18.98											
sheet		revision		J		J		J															
index		sheet		1		2		3															



BOARD PATTERN
SCALE 2/1



TAPE & REEL PACKAGING SCALE NONE
PER EIA 481-3

mat'l. code SEE NOTE 1				surface ASME Y14.5 ✓		tolerance ASME Y14.5		projection 		product family MEG-ARRAY													
ltr		ecn no		dr		date		tolerances unless otherwise specified						title									
J								angles		<div>linear</div>		X ±3				<div>mm</div>							
								XX ±13															
								0° ±2'				XXX ±051				scale 2:1							
								dr		D.WAUGHEN		9.18.98		dwg no				sheet 2 of 3				size A4	
								engr		M.HAHN		9.18.98											
								chr		M.HAHN		9.18.98											
								appd		M.HAHN		9.18.98		type				CUSTOMER Drawing					
sheet index		revision sheet																					

PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
84740-002	YES	15u" (.38um) Au OVER Ni	SnPb
84740-002LF			SnAgCu LEAD FREE (6)(7)
84740-102	YES	30u" (.76um) Au OVER Ni	SnPb
84740-102LF			SnAgCu LEAD FREE (6)(7)
84740-202	YES	SEE MATED HEIGHT TABLE (BELOW)	SnPb
84740-202LF			SnAgCu LEAD FREE (6)(7)

NOTES:

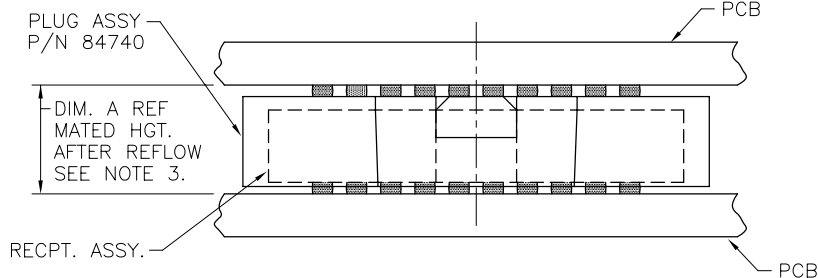
1. MAT'L:

HOUSING: LCP
CONTACT: COPPER ALLOY

PLATING:

CONTACT: (SEE TABLE ON SHEET3)
SOLDER BALL: (SEE TABLE ON SHEET3)
EUTECTIC SnPb OR LEAD FREE
95.5Sn/4Ag/0.5Cu

2. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
3. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
4. PLATING FOR INDICATED -2XX SERIES PART NOS. MEETS THE REQUIREMENTS OF NORTEL NPS25298-2 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).
5. PLATING FOR INDICATED -2XX SERIES PART NOS. IS Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.
6. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THERFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
7. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION



MATED HEIGHT TABLE		
DIM. A	RECPT. ASSY. P/N	-2XX PLATING
4.0	74221	SEE NOTE 4
6.0	74388	SEE NOTE 5
8.0	74390	SEE NOTE 5

MATED HEIGHT AFTER REFLOW IS BASED ON ϕ .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE NONE

mat'l. code SEE NOTE 1				surface ASME Y14.5 ✓	tolerance ASME Y14.5	projection 	product family MEG-ARRAY
ltr	ecr no	dr	date	tolerances unless otherwise specified			title 0mm PLUG ASSY. 10x40= 400 POS.
J				angles	time to X *3 XX *13 XXX *051		
				0° ±2°		mm	
				dr	D.WAUGHEN	9.18.98	FCI dwg no 84740 sheet 3 of 3 size A4
				enrg	M.HAHN	9.18.98	
				chr	M.HAHN	9.18.98	
				appd	M.HAHN	9.18.98	
sheet index	revision sheet						type CUSTOMER Drawing